

**Build up for Mindteck**  
**mind-20may2k11-11682**

0.0325	Copper plating layer 1		
0.0175	Copper foil layer 1	Signal	3.9356 mil trace width, 8.0644 mil seperation, 100 ohms differential
	Prepreg 1 - 2		
0.0350	Copper foil layer 2	Plane	
	Core 2 - 3		
0.0350	Copper foil layer 3	Signal	3.8169 mil trace width, 8.1831 mil seperation, 100 ohms differential
	Prepreg 3 - 4		
0.0350	Copper foil layer 4	Signal	3.8169 mil trace width, 8.1831 mil seperation, 100 ohms differential
	Core 4 - 5		
0.0350	Copper foil layer 5	Plane	
	Prepreg 5 - 6		
0.0175	Copper foil layer 6	Signal	3.9356 mil trace width, 8.0644 mil seperation, 100 ohms differential
0.0325	Copper plating layer 6		
1.6000	Total PCB thickness in mm		

**Disclaimer:** This stack-up has assumptions regarding the copper area per layer, as well as prepreg distance & dielectric constants. An impedance tolerance of +/- 10% can only be achieved if we adjust the trace width & prepreg height to meet the impedance requirement after receipt of the gerber files.